HT75Hxx 40V, 150mA TinyPower™ LDO with Protections

Features

- Low power consumption
- · Low voltage drop
- · Low temperature coefficient
- High input voltage (up to 40V)
- Output voltage accuracy: tolerance $\pm 1.5\%$
- · Soft start function
- Over current protection
- · Over temperature protection
- Package types: 3-pin SOT89, 5-pin SOT23

Applications

- Industrial/Automotive Application
- · Power Meter, Water Meter, Smart Meter
- Portable/Battery-Powered Equipment

General Description

The HT75Hxx series is a set of low power consumption high voltage regulator implemented in a BCD technology, which ensures low voltage drop and low quiescent current. They allow input voltages as high as 40V. They are available with several fixed output voltages ranging from 2.1V to 5.0V.

The soft start function controls the output slew rate to prevent the overshooting phenomenon when power on. The enable pin, CE, accepts CMOS level as logic input. When CE goes low, a fast discharging path pulls output voltage low a via 300Ω resistor. The internally output over current protection prevents the HT75Hxx from being burned even if the output node shorts to ground. The over temperature protection ensures that the junction temperature will not exceed 150°C . The soft start function inhibits the output overshooting when power on.

Selection Table

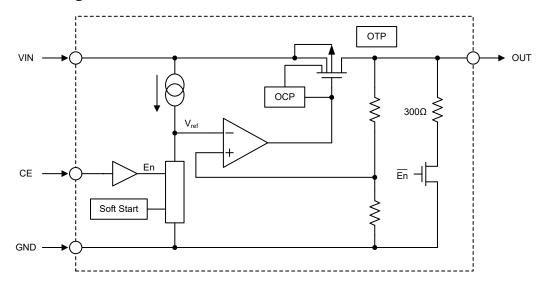
Part No.	Output Voltage	Package	Marking
HT75H21	2.1V		
HT75H23	2.3V		
HT75H25	2.5V		
HT75H27	2.7V		
HT75H30	3.0V	SOT89	HT75Hxx (for SOT89)
HT75H33	3.3V	SOT23-5	5Hxx (for SOT23-5)
HT75H36	3.6V		
HT75H40	4.0V		
HT75H44	4.4V		
HT75H50	5.0V		

Note: "xx" stands for output voltages.

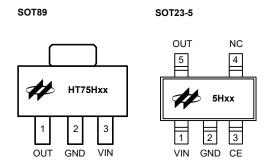
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Block Diagram



Pin Assignment



Pin Descriptions

Pin No.		Pin Name	Pin Description		
3	1	8	VIN	Input pin	
2	2	5, 9	GND	Ground pin	
1	5	1	OUT	Output pin	
_	3	7	CE	Chip enable pin, high enable	
_	4	2, 3, 4, 6	NC	No connection	



Absolute Maximum Ratings

Parameter	Value	Unit	
V _{IN}		-0.3 to +48	V
Vce	-0.3 to (V _{IN} +0.3)	V	
Operating Temperature Range, Ta		-40 to +85	°C
Maximum Junction Temperature, T _{J(MAX)}		+150	°C
Storage Temperature Range	-60 to +150	°C	
TCD Cuppontibility	Human Body Model	±5000	V
ESD Susceptibility	Machine Model	±400	V
lunation to Ambient Thermal Decistance O	SOT89	200	°C/W
Junction-to-Ambient Thermal Resistance, θ _{JA} SOT23-5		500	°C/W
Power Dissipation D	SOT89	0.625	W
Power Dissipation, P _D	SOT23-5	0.25	W

Note: P_D is measured at Ta=25°C.

Recommended Operating Range

Parameter	Value	Unit
V _{IN}	(V _{OUT} +2) to 40	V
V _{CE}	0 to V _{IN}	V

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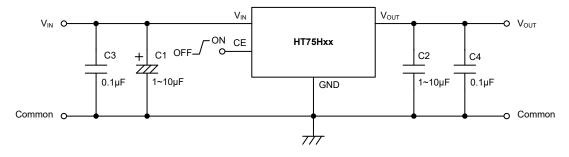


Electrical Characteristics

 $V_{IN}=V_{OUT}+2V$, $V_{CE}=V_{IN}$, $Ta=25^{\circ}C$ and $C_{IN}=C_{OUT}=1\mu F$, unless otherwise specified

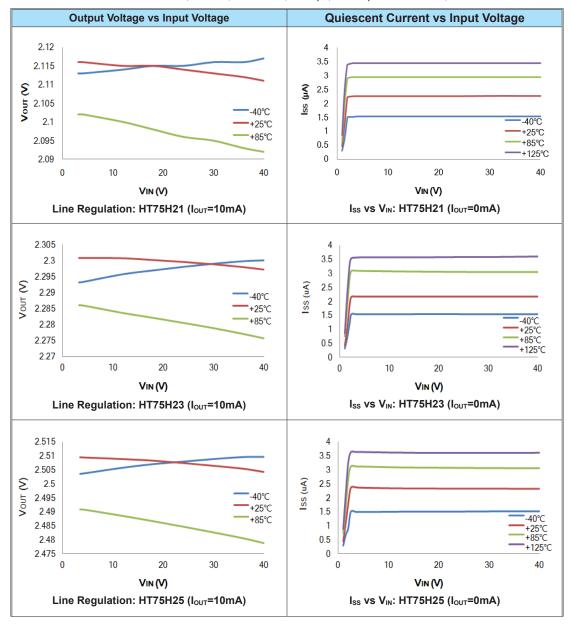
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V _{IN}	Input Voltage	_		_	40	V
V _{OUT}	Output Voltage Range	_	2.1	_	5.0	V
Vo	Output Voltage Accuracy	I _{OUT} =10mA	-1.5	_	1.5	%
	Outrout Commont	V _{OUT} =2.1V to 3.0V	100	_	_	А
Гоит	Output Current	V _{OUT} =3.3V to 5.0V		_	_	mA
ΔV_{OUT}	Load Regulation	1mA≤I _{OUT} ≤50mA	_	15	45	mV
V _{DIF}	Dropout Voltage	I _{OUT} =1mA, V _{OUT} Change=2% (Note)	_	10	30	mV
	Out a cont Comment	I _{OUT} =0mA	_	2.5	4.0	μΑ
Iss	Quiescent Current	V _{CE} =2.2V, V _{IN} =40V, I _{OUT} =0mA	_	3.0	5.0	μA
I _{SHD}	Shutdown Current	V _{CE} =0V	_	0.1	1.0	μA
$\frac{\Delta V_{\text{OUT}}}{\Delta V_{\text{IN}} \times \Delta V_{\text{OUT}}}$	Line Regulation	(V _{OUT} +1V)≤V _{IN} ≤40V, I _{OUT} =1mA	_	0.1	0.2	%/V
$\frac{\Delta V_{\text{OUT}}}{\Delta \text{Ta} \times \Delta V_{\text{OUT}}}$	Temperature Coefficient	I _{OUT} =10mA, -40°C <ta<85°c< td=""><td>_</td><td>±100</td><td>_</td><td>ppm/°C</td></ta<85°c<>	_	±100	_	ppm/°C
I _{OCP1}	OCP1 Current Threshold	V _{IN} =24V	_	250	_	mA
I _{OCP2}	OCP2 Current Threshold	V _{IN} =24V, force V _{OUT} =0V	_	150	_	mA
V _{OCP_TH}	OCP1/OCP2 Current Threshold	Observe at V _{OUT} terminal	_	0.7	_	V
T _{SHD}	Shutdown Temperature	_	_	150	_	°C
T _{REC}	Recovery Temperature	_	_	120	_	°C
V _{IH}	Enable High Threshold	CE pin, (V _{OUT} +1V)≤V _{IN} ≤40V	2	_	_	V
V _{IL}	Enable Low Threshold	CE pin, (V _{OUT} +1V)≤V _{IN} ≤40V	_	_	0.6	V
R _{DIS}	Discharge Resistor	V _{IN} =24V, CE=0V, measure at V _{OUT}	_	300	_	Ω
PSRR	Power Supply Rejection Ratio	V _{IN} =24V, V _{OUT} =5V, I _{OUT} =10mA, f=1kHz	_	60	_	dB
Noise	Output Voltage Noise	V _{OUT} =5V, I _{OUT} =10mA, BW=10Hz~100kHz	_	75	_	μV _{RMS}

Note: Dropout voltage is defined as the input voltage minus the output voltage that produces a 2% change in the output voltage from the value at $V_{IN}=V_{OUT}+2V$ with a fixed load.

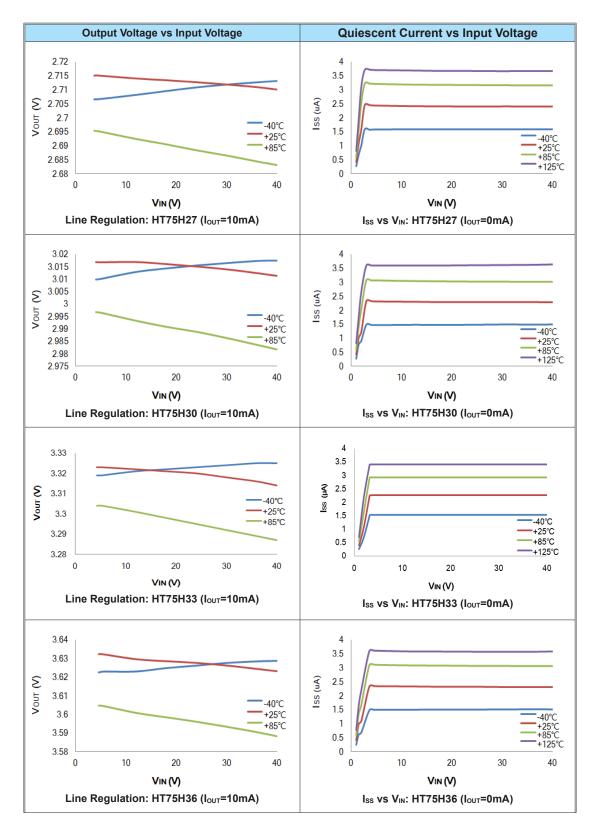




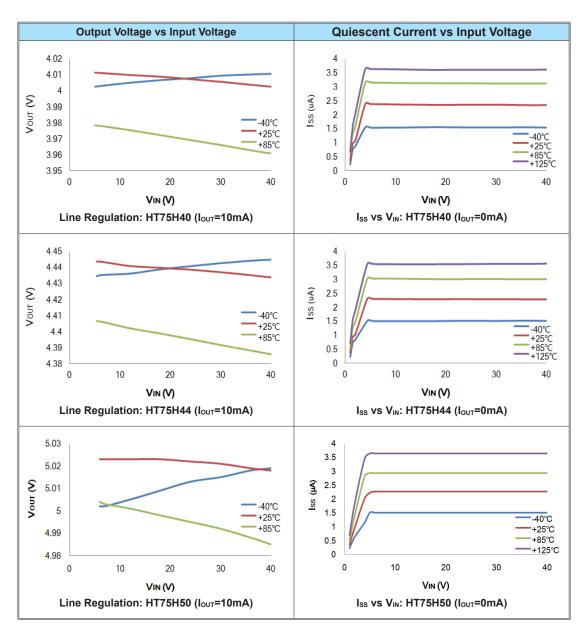
Typical Performance Characteristic



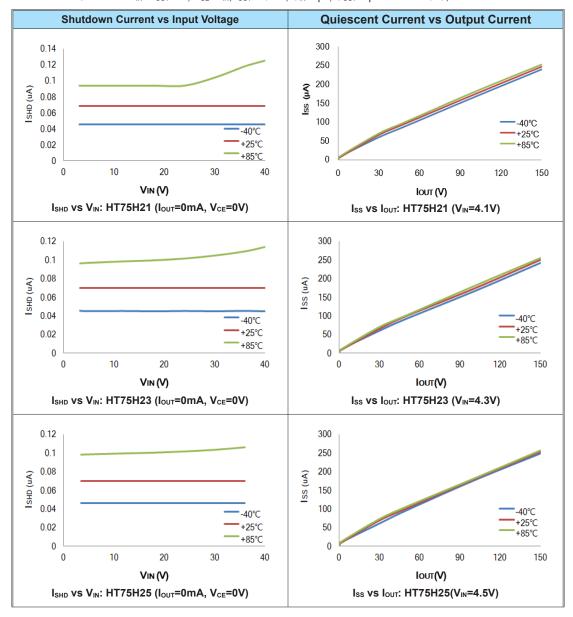




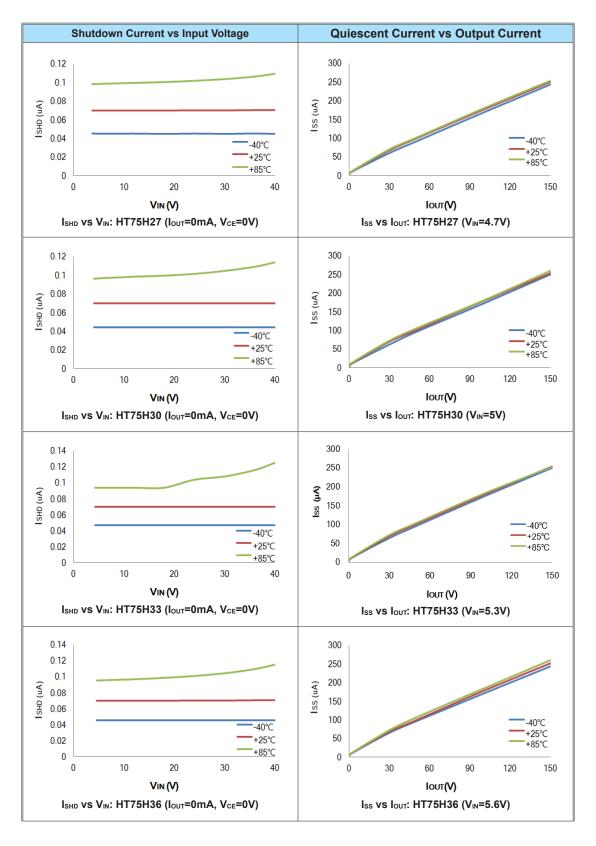




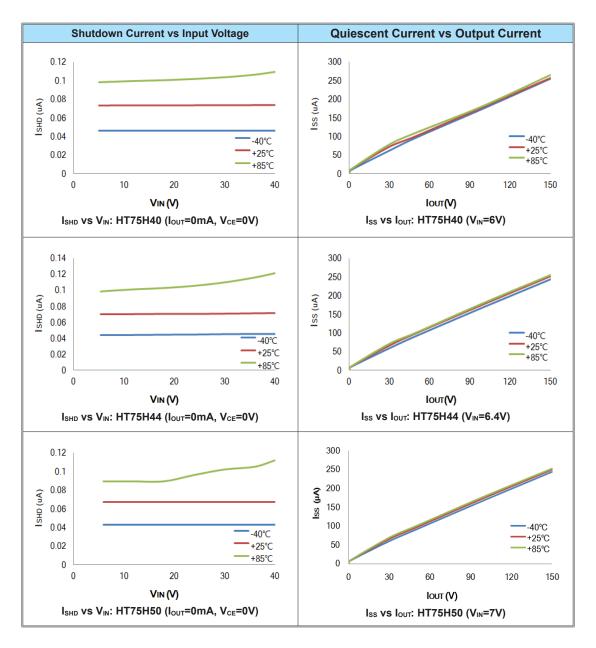






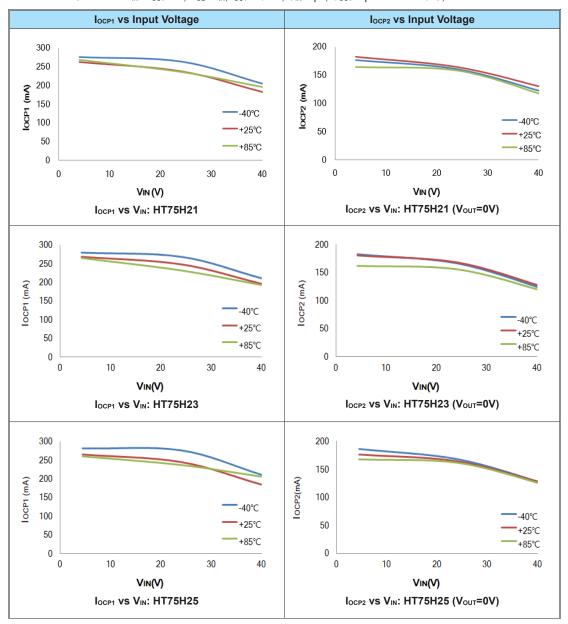




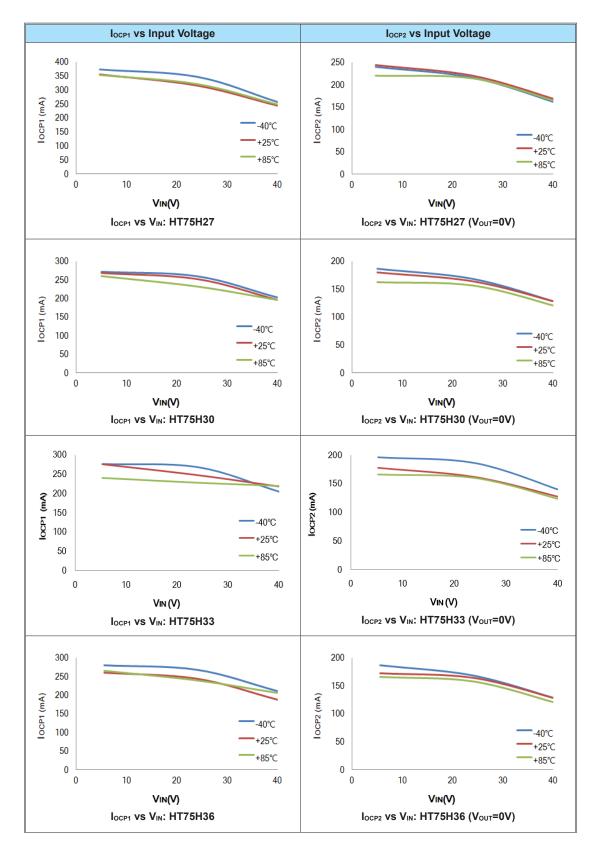




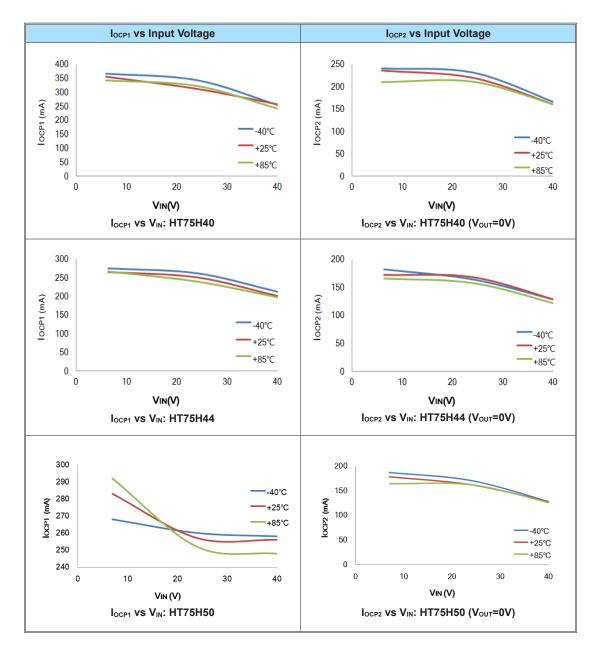
 $Test\ Condition:\ V_{IN}=V_{OUT}+2V,\ V_{CE}=V_{IN},\ I_{OUT}=10mA,\ C_{IN}=1\mu F,\ C_{OUT}=1\mu F\ and\ Ta=25^{\circ}C,\ unless\ otherwise\ noted.$





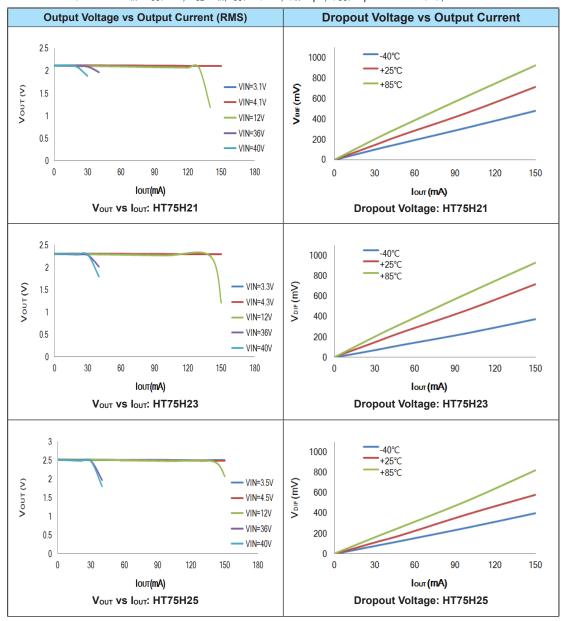




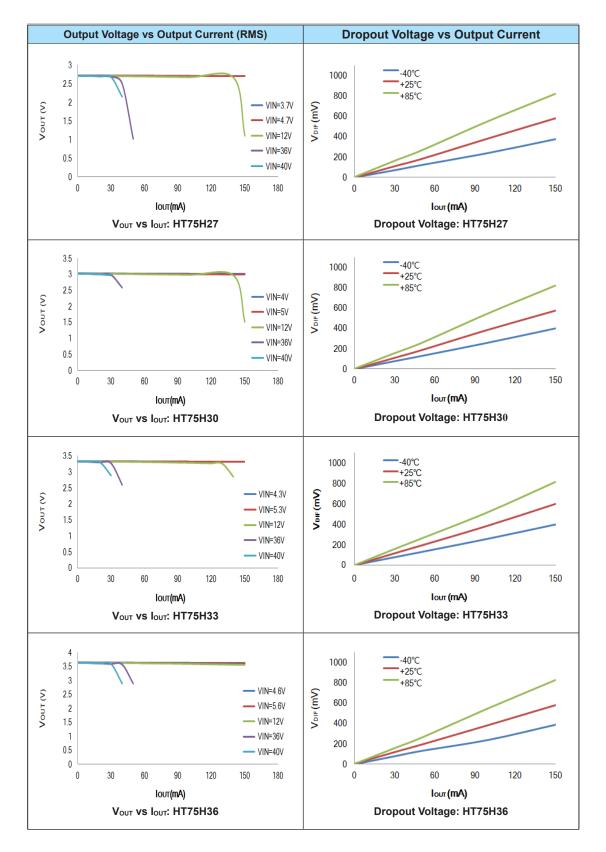




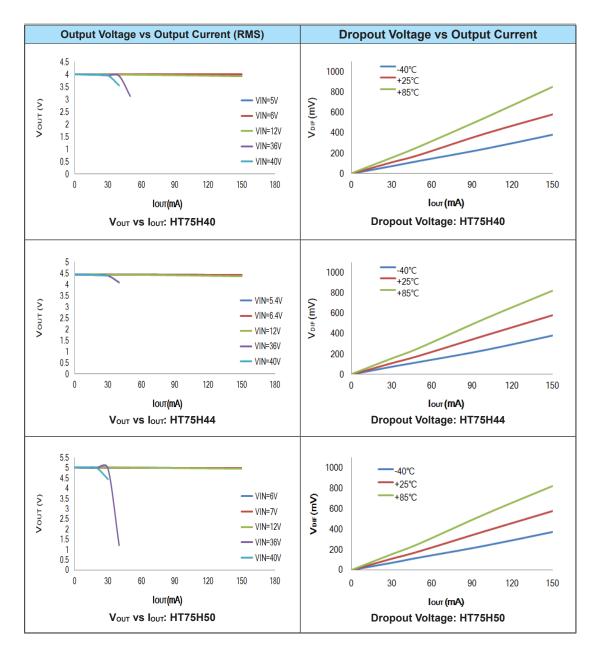
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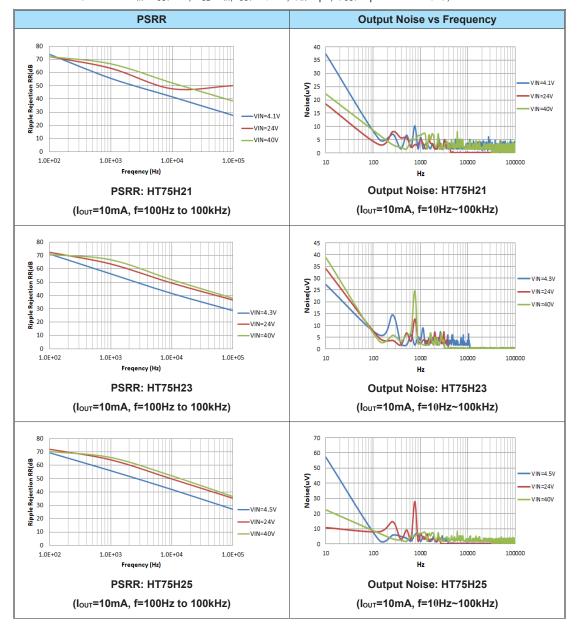




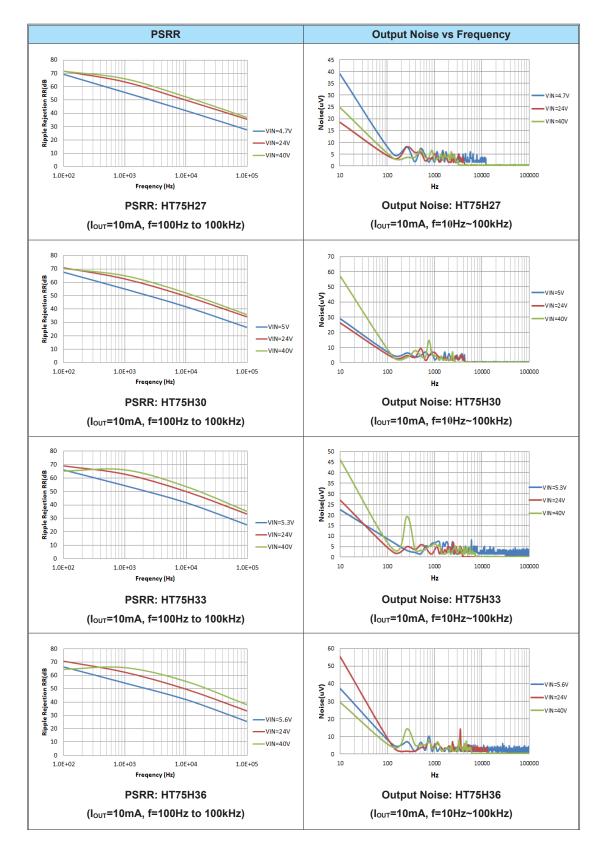




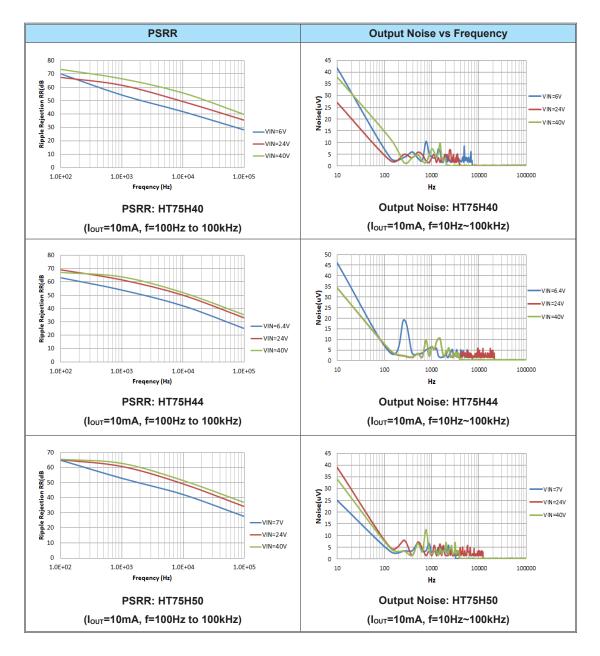






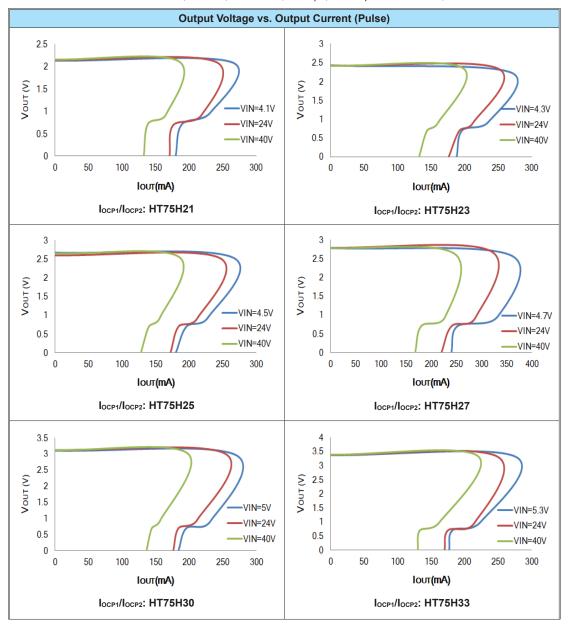




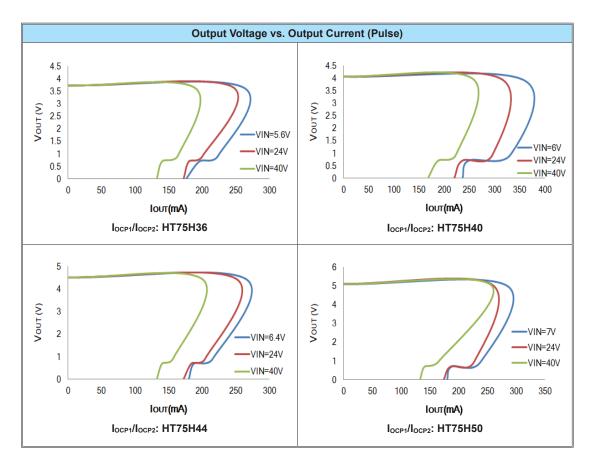




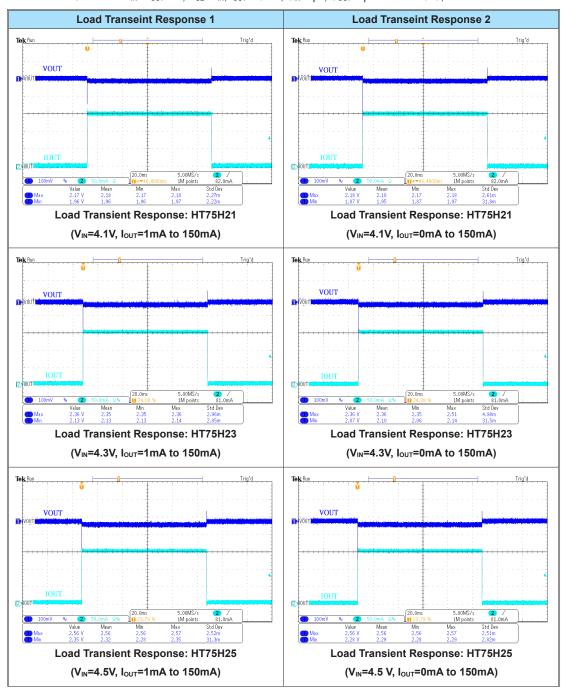
 $Test\ Condition:\ V_{IN}=V_{OUT}+2V,\ V_{CE}=V_{IN},\ I_{OUT}=10mA,\ C_{IN}=1\mu F,\ C_{OUT}=1\mu F\ and\ Ta=25^{\circ}C,\ unless\ otherwise\ noted.$



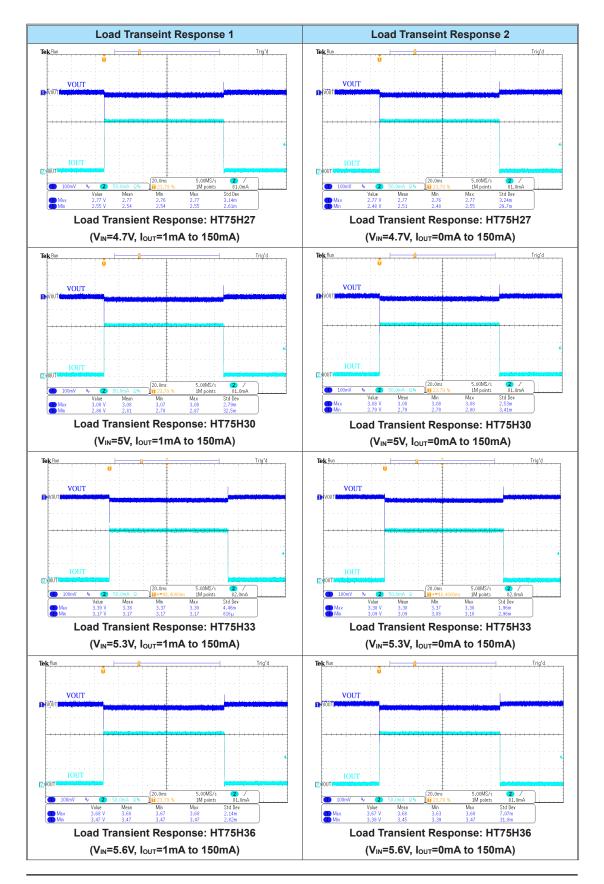




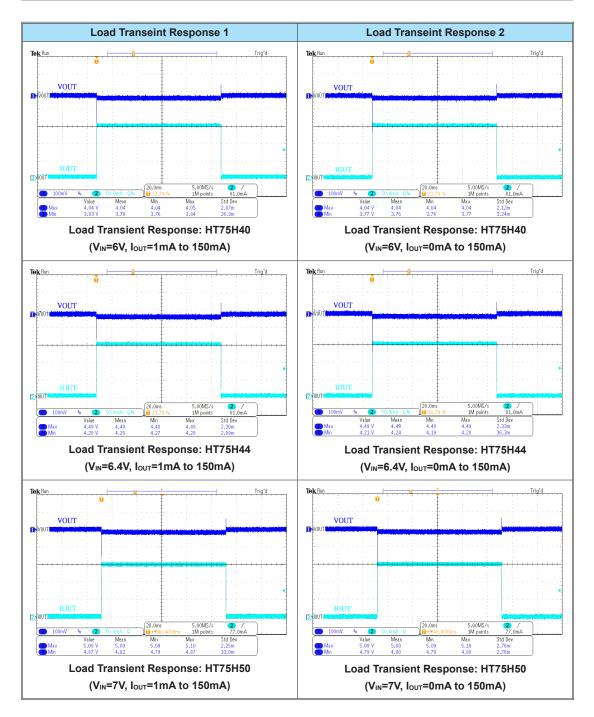




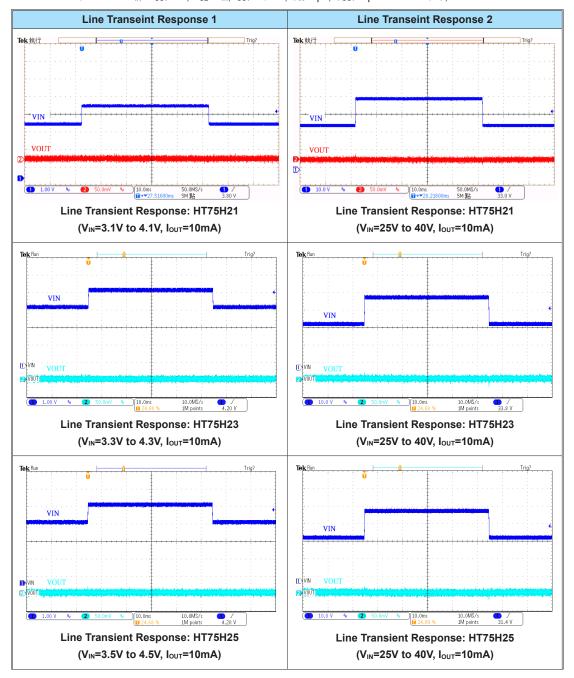




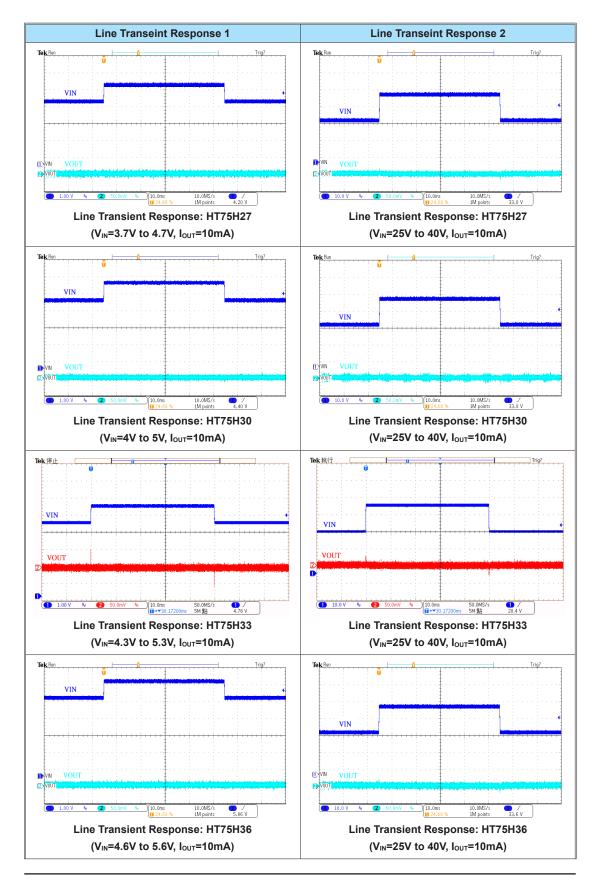




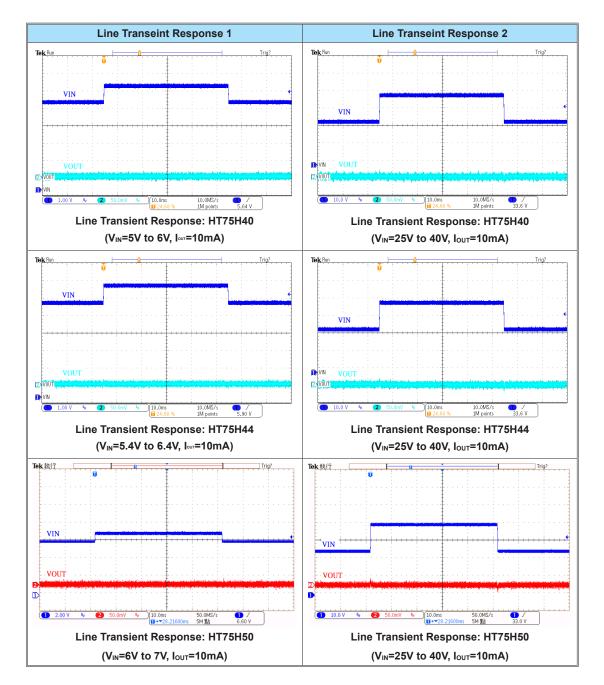




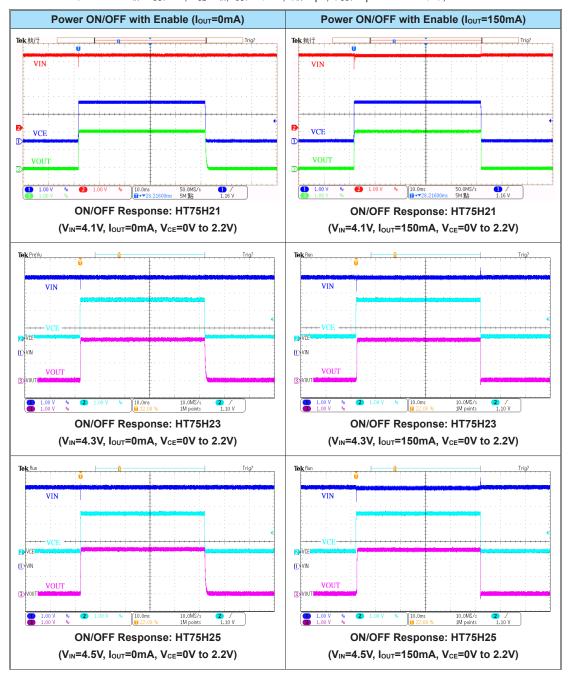




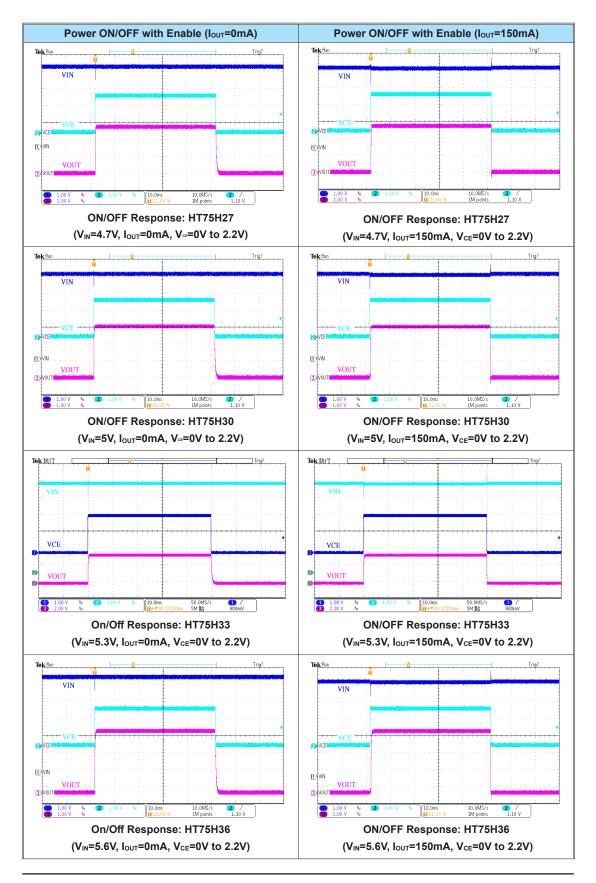




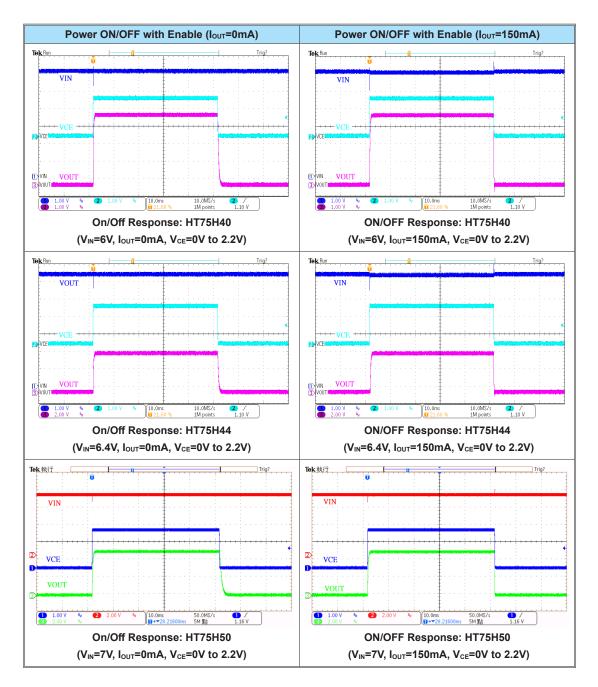




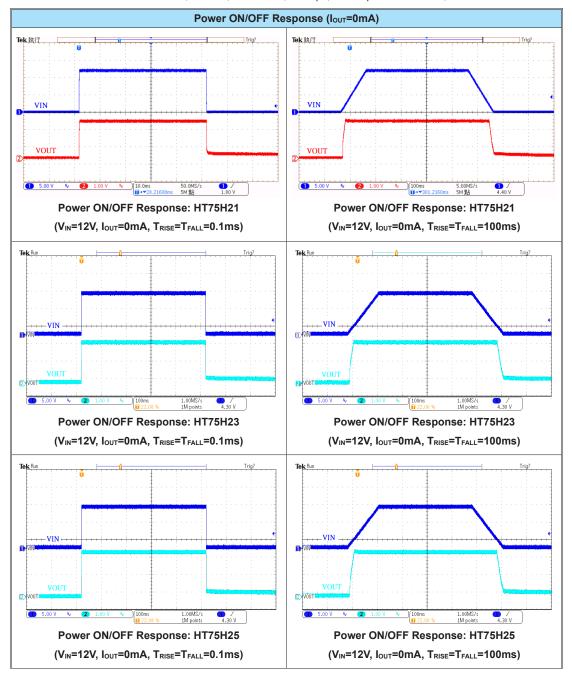




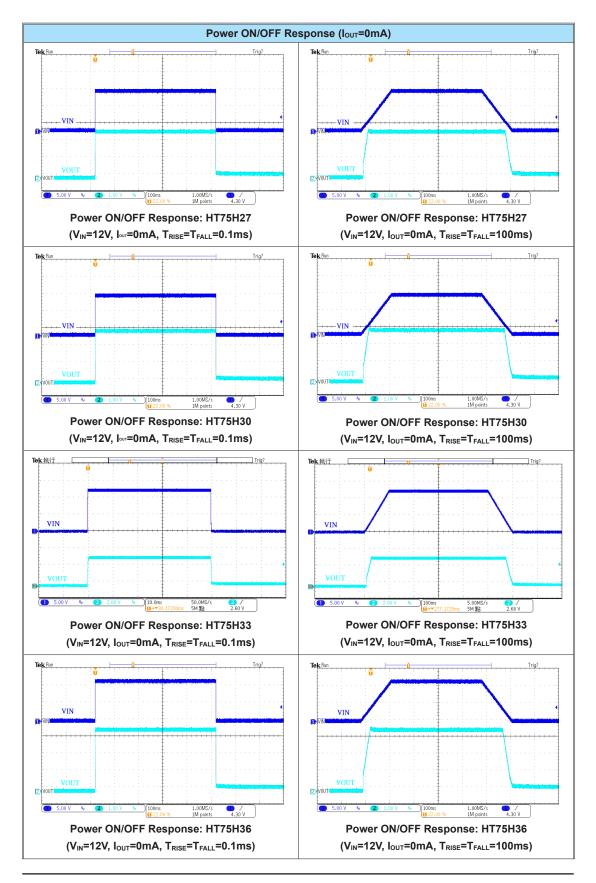




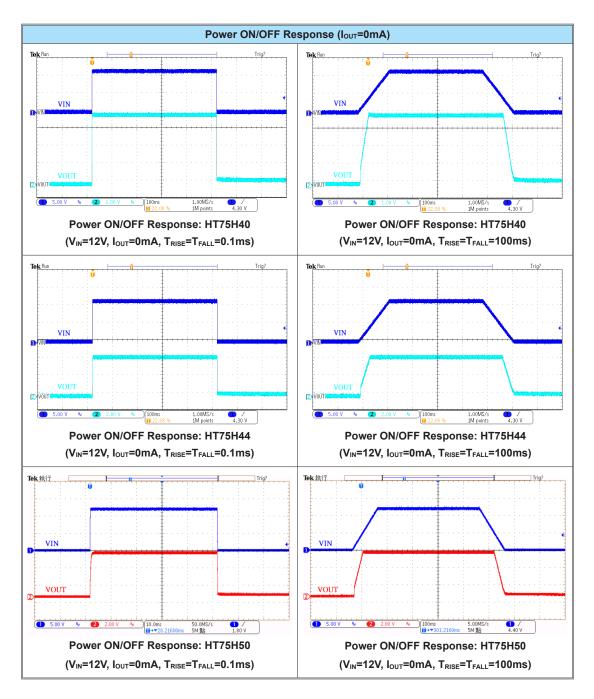




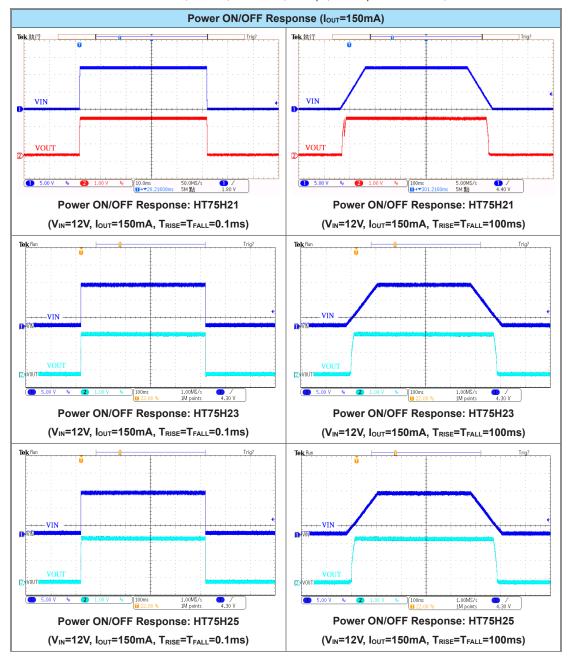




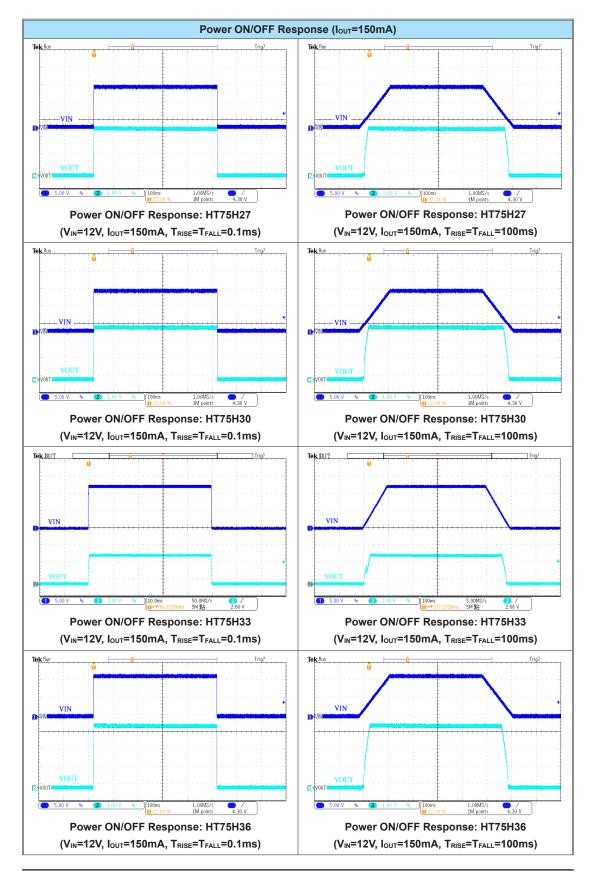




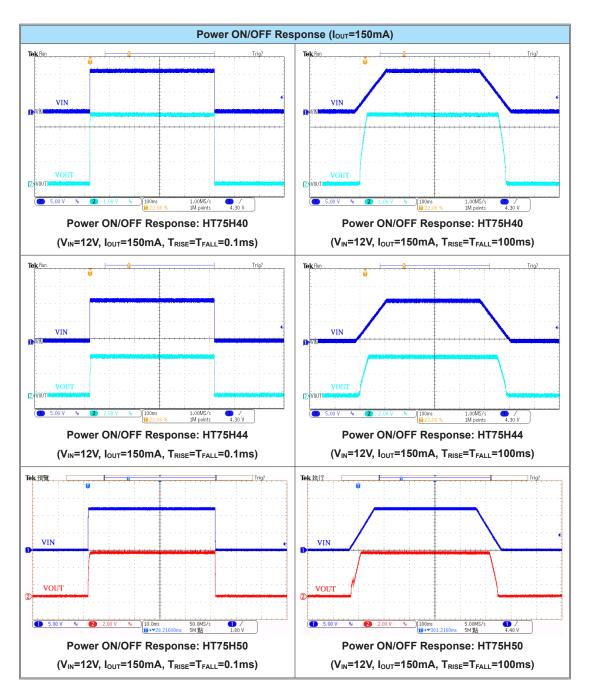












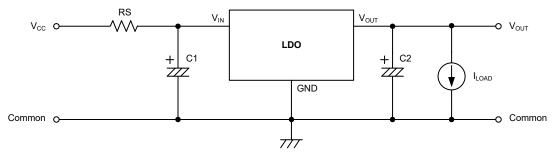


Application Information

When using the HT75Hxx regulators, it is important that the following application points are noted if correct operation is to be achieved.

Power-on Considerations

In order to suppress the output overshooting phenomenon, the rising time of input supply is suggested greater than 1ms. Adding an input resistor RS which is acting like a low-pass filter, it can slow down the rising time of the input supply in the $V_{\rm IN}$ terminal, as shown below.



The maximum RS is limited by ILOAD(MAX) and VDROPOUT. It be calculated by the following equation.

$$RS \!\! \leq \!\! \frac{V_{\text{CC}} \!\! - \! V_{\text{DROPOUT}}}{I_{\text{LOAD(MAX)}}}$$

Once the RS value is selected, the minimum value of C1 can be calculated by the following equation:

$$C1 \ge \frac{1 \text{ms}}{2.2 \text{RS}}$$

OCP and OTP Protections

The HT75Hxx implements the over current protection and over junction temperature protection to prevent IC damage even if the output is shorted to ground. When the output is shorted to ground, the output current will be clamped to I_{OCP2} and the junction temperature will rise. Once the junction temperature exceeds 150°C, the HT75Hxx will shut down the power component to prevent thermal damage. The protection will be released when the junction temperature falls to 120°C.

There are 2 levels of over current protection threshold existing in the HT75Hxx. Once the output voltage is greater than 0.7V, the OCP limit current is set to I_{OCP1} . Otherwise then the output voltage is less than 0.7V, the OCP current folds back to I_{OCP2} in order to slow down the junction temperature rises even if the output terminal is shorted to ground.

Fast Output Discharging Function

When CE='L', the output voltage will be fast discharged to 0V via an internal 300Ω resistor. This discharging path doesn't use protections such as OCP/OTP.

Input Capacitor C_{IN} Consideration

It is recommended that the input capacitor be at least $1\mu F$ and be ceramic type for better temperature coefficient and lower ESR (Equivalent Series Resistance).

Output Capacitor Cout Considerations

The output capacitance plays an important role in keeping the output voltage stable. For the ceramic type capacitor, the capacitance should be at least $1\mu F$. For the E-cap type capacitor, the capacitance should be at least $2.2\mu F$.



Thermal Considerations

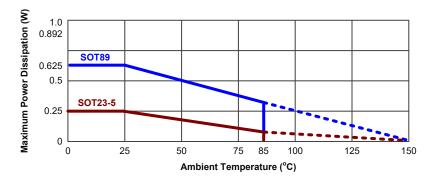
The maximum power dissipation depends on the thermal resistance of the package, the PCB layout, the rate of the surrounding airflow and the difference between the junction and ambient temperature. The maximum power dissipation can be calculated using the following formula:

$$P_{D(MAX)} = (T_{J(MAX)} - Ta) / \theta_{JA}$$

where $T_{J(MAX)}$ is the maximum junction temperature, Ta is the ambient temperature and θ_{JA} is the junction-to-ambient thermal resistance of the IC package in degrees per watt. The following table shows the θ_{JA} values for various package types.

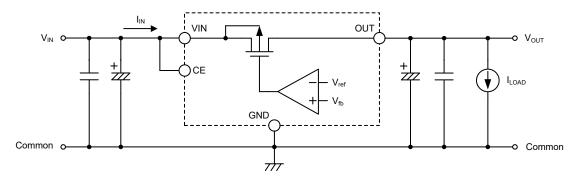
Package Type	θ _{JA} (°C/W)
SOT89	200 °C/W
SOT23-5	500 °C/W

For maximum operating rating conditions, the maximum junction temperature is 150°C. However, it is recommended that the maximum junction temperature does not exceed 125°C during normal operation to maintain an adequate margin for device reliability. The derating curves of different packages for maximum power dissipation are as follows:



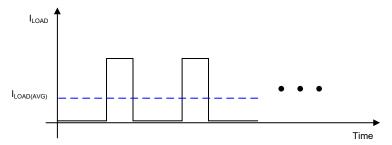
Power Dissipation Calculation

In order to keep the device within its operating limits and to maintain a regulated output voltage, the power dissipation of the device, given by P_D , must not exceed the Maximum Power Dissipation, given by $P_D(MAX)$. Therefore, $P_D \leq P_{D(MAX)}$. From the diagram it can be seen that almost all of this power is generated across the pass transistor which is acting like a variable resistor in series with the load to keep the output voltage constant. This generated power which will appear as heat, must never allow the device to exceed its maximum junction temperature.





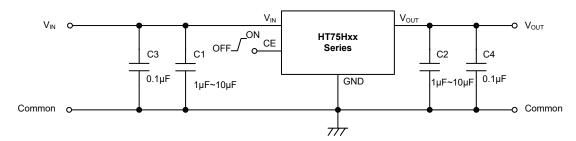
In practical applications the regulator may be called upon to provide both steady state and transient currents due to the transient nature of the load. Although the device may be working well within its limits with its steady state current, care must be taken with transient loads which may cause the current to rise close to its maximum current value. Care must be taken with transient loads and currents as this will result in device junction temperature rises which must not exceed the maximum junction temperature. With both steady state and transient currents, the important current to consider is the average or more precisely the RMS current which is the value of current that will appear as heat generated in the device. The following diagram shows how the average current relates to the transient currents.



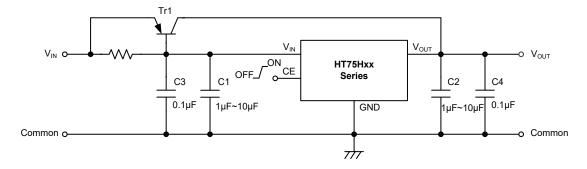
As the quiescent current of the device is very small it can generally be ignored and as a result the input current can be assumed to be equal to the output current. Therefore the power dissipation of the device, P_D , can be calculated as the voltage drop across the input and output multiplied by the current, given by the equation, $P_D=(V_{IN}-V_{OUT})\times I_{IN}$. As the input current is also equal to the load current the power dissipation $P_D=(V_{IN}-V_{OUT})\times I_{LOAD}$. However, with transient load currents, $P_D=(V_{IN}-V_{OUT})\times I_{LOAD(AVG)}$ as shown in the figure.

Application Circuits

Basic Circuits

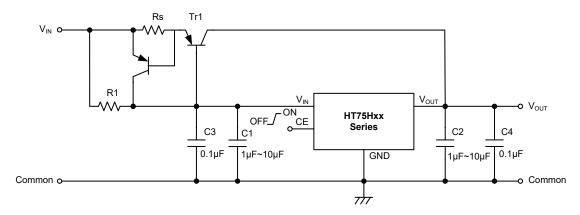


High Output Current Positive Voltage Regulator



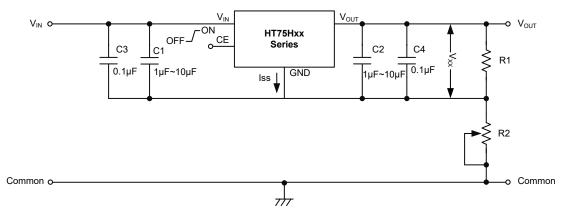


Short-Circuit Protection by Tr1

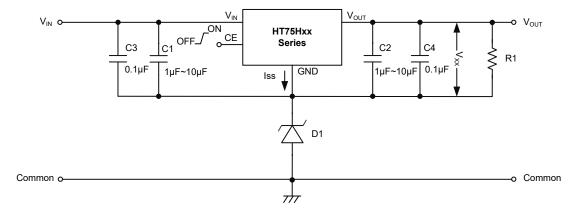


Increasing Output Voltage Circuits

 $V_{OUT} = V_{XX} \times (1+R2/R1) + I_{SS} \times R2$

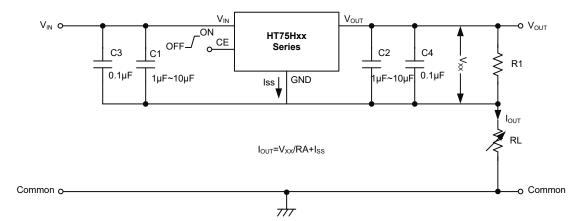


$V_{OUT} = V_{XX} + V_{D1}$

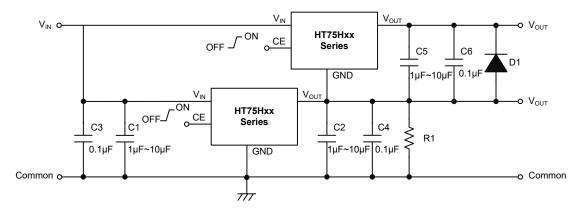




Constant Current Regulator



Dual Supply





Package Information

Note that the package information provided here is for consultation purposes only. As this information may be updated at regular intervals users are reminded to consult the <u>Holtek website</u> for the latest version of the <u>package information</u>.

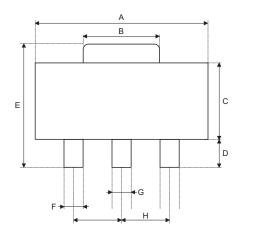
Additional supplementary information with regard to packaging is listed below. Click on the relevant section to be transferred to the relevant website page.

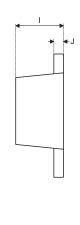
- Further Package Information (include Outline Dimensions, Product Tape and Reel Specifications)
- Packing Meterials Information
- Carton information

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3-pin SOT89 Outline Dimensions



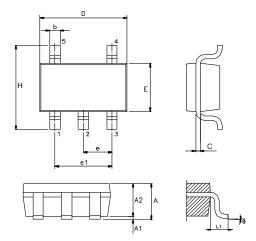


Cumbal	Dimensions in inch			
Symbol	Min.	Nom.	Max.	
A	0.173	_	0.185	
В	0.053	_	0.072	
С	0.090	_	0.106	
D	0.031	_	0.047	
E	0.155	_	0.173	
F	0.014	_	0.019	
G	0.017	_	0.022	
Н	_	0.059 BSC	<u> </u>	
I	0.055	_	0.063	
J	0.014	_	0.017	

Symbol	Dimensions in mm			
Syllibol	Min. Nom.		Max.	
A	4.40	_	4.70	
В	1.35	_	1.83	
С	2.29	_	2.70	
D	0.80	_	1.20	
E	3.94	_	4.40	
F	0.36	_	0.48	
G	0.44	_	0.56	
Н	_	1.50 BSC	_	
I	1.40	_	1.60	
J	0.35	_	0.44	



5-pin SOT23 Outline Dimensions



Symbol	Dimensions in inch			
Symbol	Min.	Nom.	Max.	
А	_	_	0.057	
A1	_	_	0.006	
A2	0.035	0.045	0.051	
b	0.012	_	0.020	
С	0.003	_	0.009	
D	_	0.114 BSC	_	
Е	_	0.063 BSC	_	
е	_	0.037 BSC	_	
e1	_	0.075 BSC	_	
Н	_	0.110 BSC	_	
L1	_	0.024 BSC	_	
θ	0°	_	8°	

Cumbal	Dimensions in mm				
Symbol	Min.	Nom.	Max.		
A	_	_	1.45		
A1	_	_	0.15		
A2	0.90	1.15	1.30		
b	0.30	_	0.50		
С	0.08	_	0.22		
D	_	2.90 BSC	_		
Е	_	1.60 BSC	_		
е	_	0.95 BSC	_		
e1	_	1.90 BSC	_		
Н	_	2.80 BSC	_		
L1	_	0.60 BSC	_		
θ	0°	_	8°		

Rev. 1.30 44 May 12, 2023



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